

AMENDMENTS TO THE CLAIMS

Claim 1. (Canceled)

2. (New) A substrate plating apparatus for electrolessly plating a surface of a semiconductor substrate with metal, said apparatus comprising:

a plating area including at least one plating chamber for containing a plating solution for electrolessly plating a semiconductor substrate with metal;

a cleaning and drying area including at least one cleaning unit comprising a cleaner with a sponge layer for cleaning a plated semiconductor substrate; and

a partition disposed between said plating area and said cleaning and drying area, wherein pressure in said cleaning and drying area is greater than pressure in said plating area.

3. (New) The substrate plating apparatus according to claim 2, further comprising: a concentration analyzing device to analyze concentrations of components of the plating solution.

4. (New) The substrate plating apparatus according to claim 3, wherein said concentration analyzing device includes a metal ion concentration analyzer and a plating additive concentration analyzer.

5. (New) The substrate plating apparatus according to claim 4, further comprising: a plating solution preparing device to prepare the plating solution based on the concentration as analyzed by said concentration analyzing device.

6. (New) The substrate plating apparatus according to claim 5, further comprising:
a loading and unloading area, wherein said cleaning and drying area is disposed between
said loading and unloading area and said plating area.

7. (New) The substrate plating apparatus according to claim 6, further comprising:
a concentration analyzing device to analyze concentrations of components of the plating
solution.

8. (New) The substrate plating apparatus according to claim 7, further comprising:
a chemical mechanical polishing unit.

9. (New) The substrate plating apparatus according to claim 8, wherein
said plating area includes at least one pretreatment chamber.

10. (New) The substrate plating apparatus according to claim 9, further comprising:
a plating solution preparing device to prepare the plating solution based on the
concentration as analyzed by said concentration analyzing device.

11. (New) The substrate plating apparatus according to claim 10, wherein
said cleaner is a pencil-shaped cleaner or a roller.

12. (New) The substrate plating apparatus according to claim 11, wherein
air is to flow downwardly in said plating area.

13. (New) The substrate plating apparatus according to claim 12, wherein
air is to flow downwardly in said cleaning and drying area.

14. (New) The substrate plating apparatus according to claim 9, wherein said concentration analyzing device includes a metal ion concentration analyzer and a plating additive concentration analyzer.
15. (New) The substrate apparatus according to claim 3, further comprising: a plating solution preparing device to prepare the plating solution based on the concentration as analyzed by said concentration analyzing device.
16. (New) The substrate plating apparatus according to claim 2, wherein said plating area includes at least one pretreatment chamber.
17. (New) The substrate plating apparatus according to claim 2, further comprising: a loading and unloading area, wherein said cleaning and drying area is disposed between said loading and unloading area and said plating area.
18. (New) The substrate plating apparatus according to claim 2, wherein said cleaner is a pencil-shaped cleaner or a roller.
19. (New) The substrate plating apparatus according to claim 2, further comprising: a chemical mechanical polishing unit.
20. (New) The substrate plating apparatus according to claim 2, wherein air is to flow downwardly in said plating area.
21. (New) The substrate plating apparatus according to claim 2, wherein air is to flow downwardly in said cleaning and drying area.